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BGF104C

HSMMC Interface Filter and ESD Protection

RF & Protection Devices



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BGF104C

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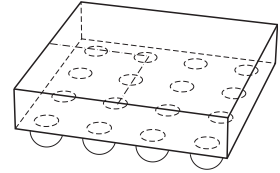
Previous Version: 2009-09-14, V1.0

Page	Subjects (major changes since last revision)
4	3D-figure of package updated
5	Figure 2 updated
6	Footprint (Figure 3) added
6	Tape specification (Figure 4) added
all	Target status removed

BGF104C

Features

- ESD protection and filter for High Speed Multi Media Card interface
- ESD protection according to IEC61000-4-2 for ± 15 kV contact discharge on external IOs
- 16 pin green wafer level package with SnAgCu solder balls
- RoHS and WEEE compliant package
- 500 μm solder ball pitch
- 300 μm solder ball diameter



WLP-16-3-N



Description

BGF104C is an ESD protection and filter circuit for a high speed multi media card interface. External pins are protected against ESD pulses of ± 15 kV contact discharge according to IEC61000-4-2. The wafer level package is a green leadfree package with a size of only 1.92 mm x 1.92 mm and a total height of 0.65 mm.

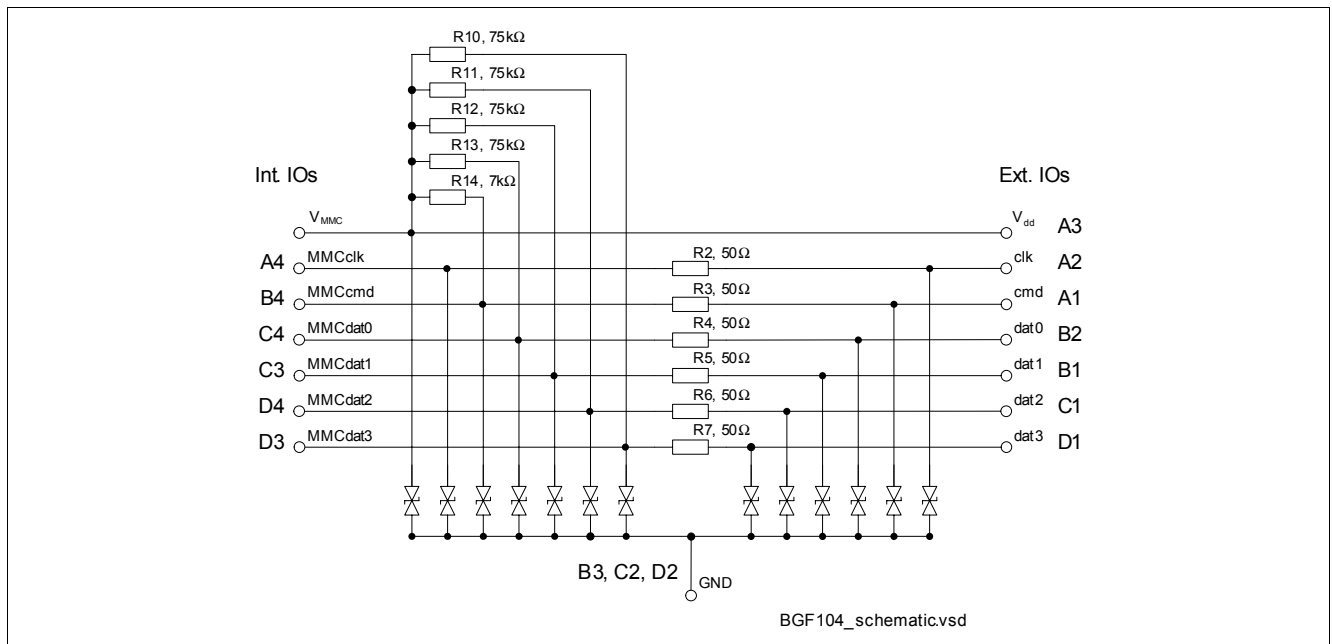


Figure 1 Schematic

Type	Package	Marking	Chip
BGF104C	WLP-16-3	4C	N0708

Table 1 Maximum Ratings

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Voltage at all pins to GND	V_P	0	–	14	V	–
Operating temperature range	T_{OP}	-40	–	+85	°C	–
Storage temperature range	T_{STG}	-65	–	+150	°C	–
Electrostatic Discharge According to IEC61000-4-2						
Contact discharge external pins to GND (A1, A2, A3, B1, B2, C1, D1)	V_{ESD}	-15	–	15	kV	–
Contact discharge internal pins to GND (A4, B4, C3, C4, D3, D4)	V_{ESD}	-2	–	2	kV	–

Table 2 Electrical Characteristics¹⁾

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Resistors $R_2 \dots R_7$	$R_{2\dots7}$	40	50	60	Ω	–
Resistors $R_{10} \dots R_{13}$	$R_{10\dots13}$	52.5	75	97.5	k Ω	–
Resistor R_{14}	R_{14}	4.9	7	9.1	k Ω	–
Line capacitance, each line to GND ²⁾	C_T	–	16	20	pF	$V = 0\text{ V}$
Reverse current of ESD protection diodes $I_R = 3\text{ V}$ $I_R = 14\text{ V}$	I_R	–	5 0.1	100 10	nA μA	–

- 1) at $T_A = 25\text{ °C}$
- 2) Without line coupling by Resistors $R_7 - R_{11}$

Package Outlines

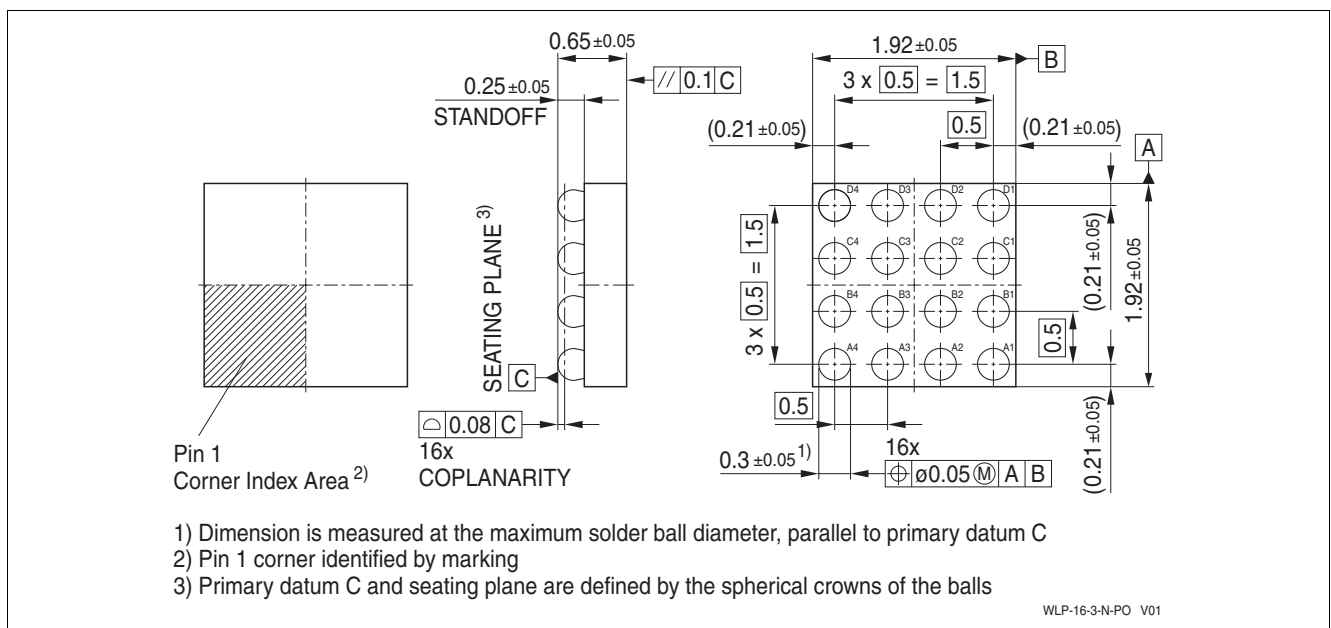


Figure 2 WLP-16-3 (dimensions in mm)

Footprint

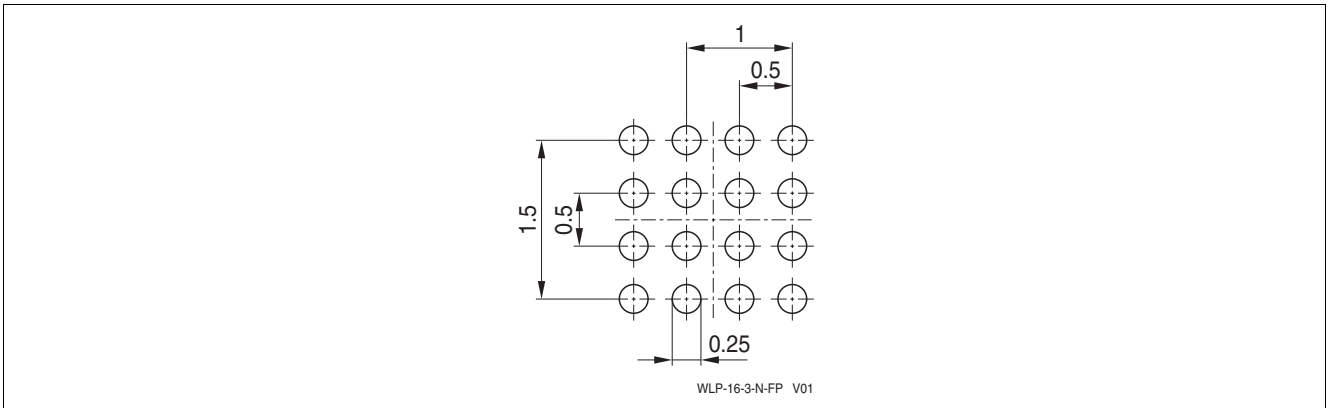


Figure 3 Footprint for WLP-16-3 (dimensions in mm)

Tape and reel specification

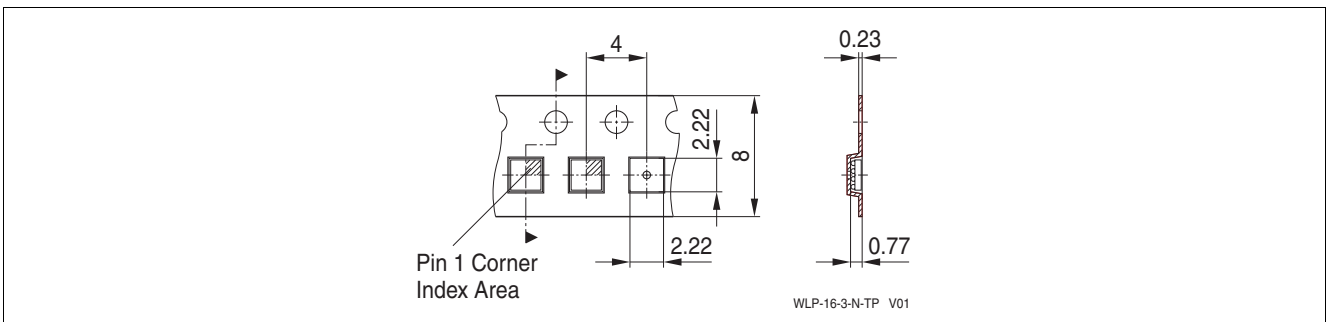


Figure 4 Tape for WLP-16-3 (dimensions in mm)

You can find all of our packages, sorts of packing and others in our Infineon Internet Page "Products": <http://www.infineon.com/products>